2SD0874G

Silicon NPN epitaxial planar type

For low-frequency power amplification Complementary to 2SB0766G

■ Features

- Large collector power dissipation P_C
- ullet Low collector-emitter saturation voltage $V_{CE(sat)}$
- Mini power type package, allowing downsizing of the equipment and automatic insertion through the tape packing and the magazine packing

■ Absolute Maximum Ratings T_a = 25°C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V _{CBO}	60	V	
Collector-emitter voltage (Base open)	V_{CEO}	50	V	
Emitter-base voltage (Collector open)	V_{EBO}	5	V	
Collector current	I_{C}	1	A	
Peak collector current	I_{CP}	1.5	A	
Collector power dissipation *	P_{C}	1	W	
Junction temperature	T_{j}	150	°C	
Storage temperature	T _{stg}	-55 to +150	°C	

Note) *: Printed circuit board: Copper foil area of 1 cm² or more, and the board thickness of 1.7 mm for the collector portion

Package

- Code
- MiniP3-F2
- Pin Name
 - 1: Base
 - 2: Collector
- 3: Emitter
- Marking Symbol: Y

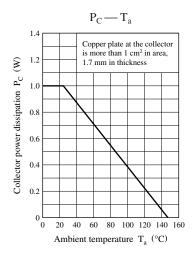
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

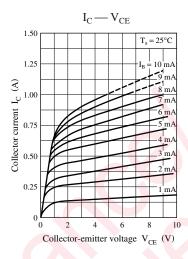
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V_{CBO}	$I_C = 10 \mu\text{A}, I_E = 0$	60	5		V
Collector-emitter voltage (Base open)	V_{CEO}	$I_C = 2 \text{ mA}, I_B = 0$				V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = 10 \mu A, I_C = 0$				V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = 20 \text{ V}, I_{E} = 0$			0.1	μΑ
Forward current transfer ratio *1	h _{FE1} *2	V _{CE} = 10 V, I _C = 500 mA	85		340	_
	h _{FE2}	$V_{CE} = 5 \text{ V}, I_{C} = 1 \text{ A}$	50			
Collector-emitter saturation voltage *1	V _{CE(sat)}	$I_C = 500 \text{ mA}, I_B = 50 \text{ mA}$		0.2	0.4	V
Base-emitter saturation voltage *1	V _{BE(sat)}	$I_C = 500 \text{ mA}, I_B = 50 \text{ mA}$		0.85	1.2	V
Transition frequency	f_T	$V_{CB} = 10 \text{ V}, I_{E} = -50 \text{ mA}, f = 200 \text{ MHz}$		200		MHz
Collector output capacitance	C _{ob}	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$			20	pF
(Common base, input open circuited)						

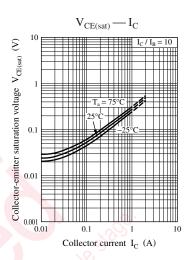
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

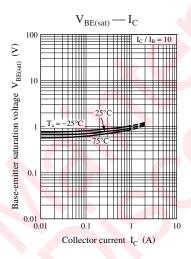
- 2. *1: Pulse measurement
 - *2: Rank classification

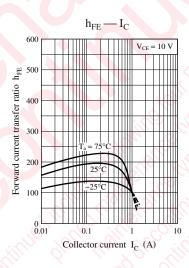
Rank	Q	R	S
h_{FE1}	85 to 170	120 to 240	170 to 340

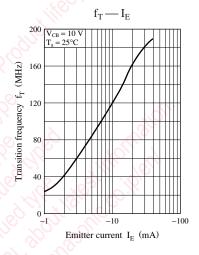


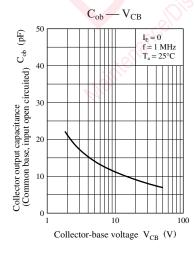


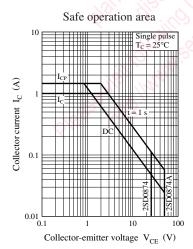






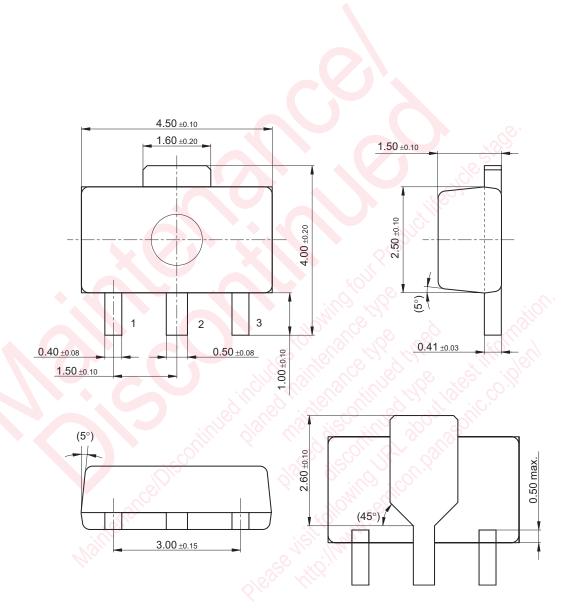






2 SJD00336AED

MiniP3-F2 Unit: mm



SJD00336AED 3

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